



TEXAS INSTRUMENTS

TI DN 2510301
Rev D
April 2016

**Circuit Card Assembly
DLP® Discovery™ 4100 Main Board**

DLP Discovery 4100 Circuit Card Assembly Main Board

Revision History

| Rev | Section | Revisions |
|-----|---------|-------------------------------|
| A | All | Initial release |
| B | | Updated schematic and BOM_CCA |
| C | | Not released |
| D | | Updated Schematic and BOM |

DLP Discovery 4100 Circuit Card Assembly Main Board

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DLP Discovery 4100 Circuit Card Assembly Main Board

1. Configuration Summary

| Dash # | Configuration Description – Reference 2510301-bom_CCA.xls |
|--------|---|
| -1 | Initial |
| -2 | Updated BOM_CCA and schematic to rev B |
| -3 | Updated BOM and Schematic to Rev D |
| | |

2. Related Documents

Texas Instruments Documents

| Dwg. Number | Document Name |
|-------------------------|---|
| 2510300 | PCB, DMD Discovery 4100 |
| 2510299 | ESD(schematic) Rev D, DMD Discovery 4100 |
| DLPC410 | DLPC410 Controller data sheet |
| DLPR410 | DLPR410 PROM data sheet |
| DLPA200 | DLPA200 DMD Micromirror driver data sheet |

3. Notes

1. This PWB contains devices that are electrostatic discharge sensitive.
2. Mark the appropriate msn. Method and placement location optional.
3. Mark dash number and revision letter of cca. Method and placement location optional.
4. Primary side components have reference designators numbered less than 500. Secondary side components have reference designators numbered greater than 500.
5. Reference designators not installed.
6. Equivalent or better part may be substituted.
7. Workmanship shall be in accordance with ansi/IPC-A-610B class 2 and ANSI/J-STD-001A class 2.
8. Solder times and temperatures must be in conformance with PWB UL component recognition limits established for the particular board.
9. Set the Jumpers to the following position
J2: all 5 positions set to 1-2 (side closest to JTAG)
J4: OPEN
J5: 2-3
J10: 1-2 for 1080p, OPEN for XGA
J11: OPEN
10. Manufacturer's Serial Number (MSN) – T40-wwyy-nnn
T40 – Factory internal code

DLP Discovery 4100 Circuit Card Assembly Main Board

ww – Week of year (1-53)
yy – Year (2009 is '09')
nnn – Serialized code

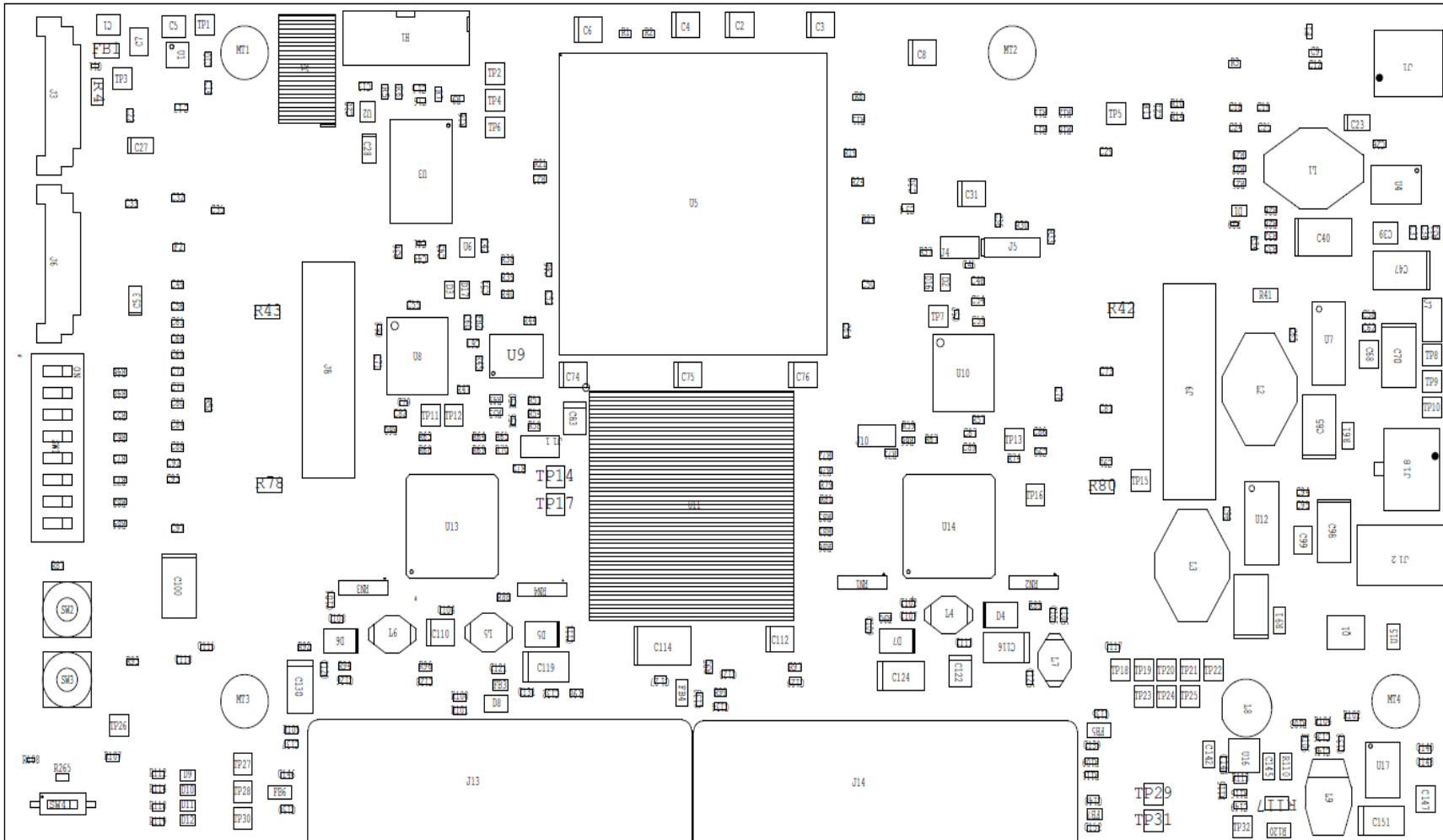
Bill of Material

See DISCOVERY 4100_BOM_Rev_D.xls.

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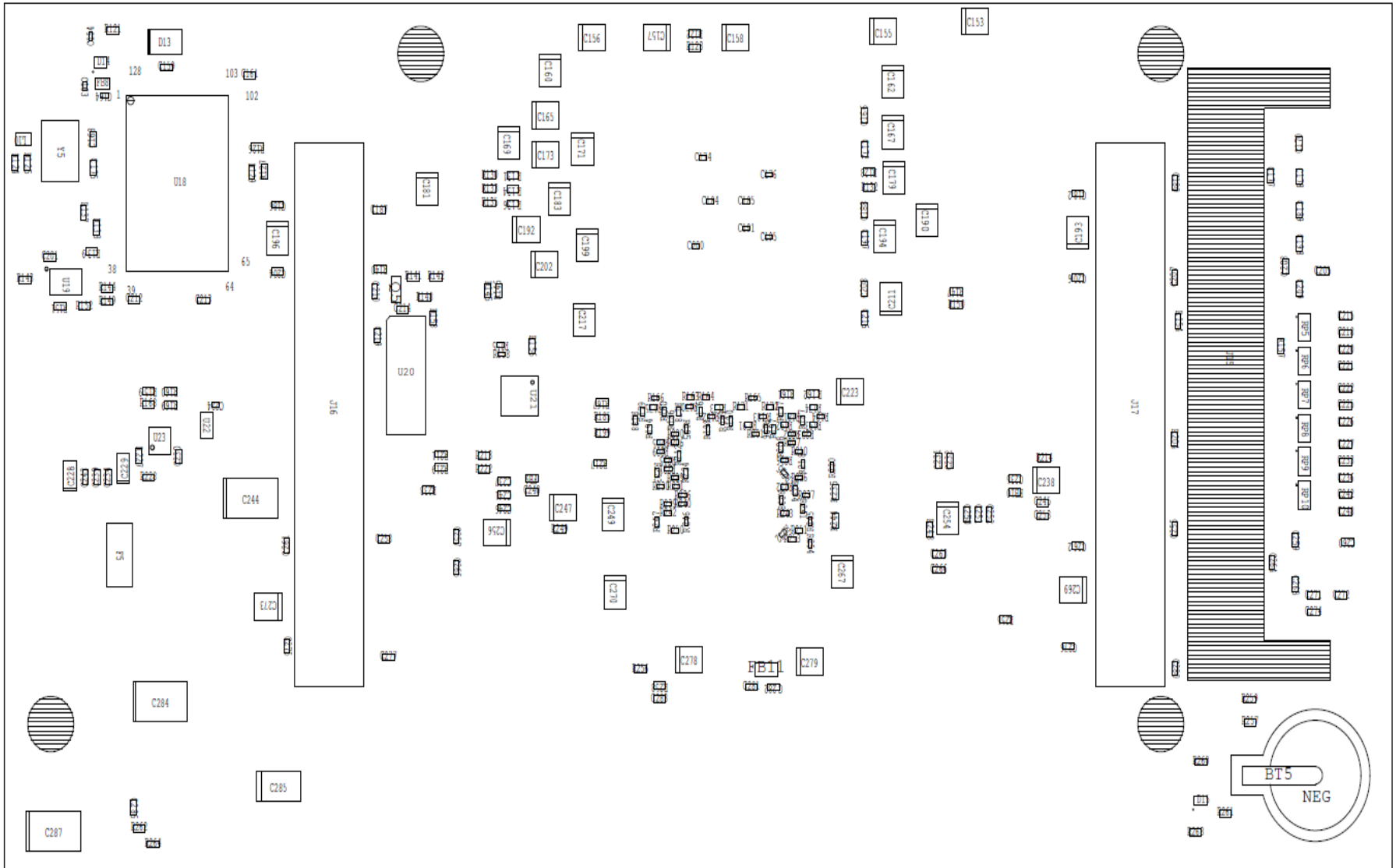
6. Assembly View

6.1 Primary Side



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6.2 Secondary Side



DLP Discovery 4000 Circuit Card Assembly Main Board

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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